What is claimed is:

1. An inspection method of inspecting an exposure pattern or mask for exposing a predetermined pattern by an exposure beam, comprising the steps of:

disposing a plurality of inspection pattern portions inside and/or outside a mask pattern portion of said exposure pattern or mask, said inspection pattern portion having a same pattern as at least a part of said mask pattern portion; and

comparing said at least a part of said mask pattern portion with said inspection pattern portion or portions.

2. The inspection method according to claim 1, wherein the number of said inspection pattern portions is a twofold or more of the number of said at least a part of said mask pattern portion.

3. The inspection method according to claim 1, wherein said inspection pattern portions are disposed near said mask pattern portion.

4. The inspection method according to claim 1, wherein said mask pattern portion has through holes arranged to form a predetermined pattern through which said exposure beam transmits, and said inspection pattern portions have recesses arranged to form a corresponding pattern.

5. The inspection method according to claim 4, wherein said mask pattern portion is made of a thin film, and said inspection pattern portions are made of the thin film on a support member.

6. The inspection method according to claim 1, wherein said at least a part of said mask pattern and said inspection pattern portion or portions are optically detected and compared detected information.

7. The inspection method according to claim 1, wherein the inspection method is used for chip comparison inspection (inspection by a "Die to Die" method) or cell comparison inspection (inspection by a "Cell to Cell" method).

8. A manufacture method of manufacturing an exposure pattern or mask for exposing a predetermined pattern by an exposure beam, comprising the steps of:

disposing a plurality of inspection pattern portions inside and/or outside a mask pattern portion of said exposure pattern or mask, said inspection pattern portion having a same pattern as at least a part of said mask pattern portion; and

comparing said at least a portion of said mask pattern portion with said inspection pattern portion or portions.

9. The manufacture method according to claim 8, wherein the number of said inspection pattern portions is a twofold or more of the number of said at least a part of said mask pattern portion.

10. The manufacture method according to claim 8, wherein said inspection pattern portions are disposed near said mask pattern portion.

11. The manufacture method according to claim 8, wherein said mask pattern portion has through holes arranged to form a predetermined pattern through which said exposure beam transmits, and said inspection pattern portions have recesses arranged to form a corresponding pattern.

12. The manufacture method according to claim 11, wherein said mask pattern portion is made of a thin film, and said inspection pattern portions are made of the thin film on a support member.

13. The manufacture method according to claim 8, wherein said at least a portion of mask pattern and said inspection pattern portion or portions are optically detected and compared detected information.

14. The manufacture method according to claim 8, wherein a manufacture condition is controlled in accordance with said comparison result.

15. The manufacture method according to claim 8, wherein said manufacture method is used for chip comparison inspection (inspection by a "Die to Die" method) or cell comparison inspection (inspection by a "Cell to Cell" method).

16. An exposure pattern or mask for exposing a predetermined pattern by an exposure beam, wherein

a plurality of inspection pattern portions are disposed inside and/or outside a mask pattern portion of said exposure pattern or mask, said inspection pattern portion

having a corresponding pattern as a pattern of said at least a part of mask pattern portion.

17. The exposure pattern or mask according to claim 16, wherein the number of said inspection pattern portions is a twofold or more of the number of said at least a portion of mask pattern portion.

18. The exposure pattern or mask according to claim 16, wherein said inspection pattern portions are disposed near said mask pattern portion.

19. The exposure pattern or mask according to claim 16, wherein said mask pattern portion has through holes arranged to form a predetermined pattern through which said exposure beam transmits, and said inspection pattern portions have recesses arranged to form a corresponding pattern.

20. The exposure pattern or mask according to claim 16, wherein said mask pattern portion is made of a thin film, and said inspection pattern portions are made of the thin film on a support member.

21. The exposure pattern or mask according to claim 16, wherein said at least a portion of mask pattern and said inspection pattern portion or portions are compared.

22. The exposure pattern or mask according to claim 16, wherein said at least a portion of mask pattern and said inspection pattern portion or portions are optically detected and compared detected information.

23. The exposure pattern or mask according to claim 16, wherein said inspection method is used for chip comparison inspection (inspection by a "Die to Die" method) or cell comparison inspection (inspection by a "Cell to Cell" method).